

# P54/74FCT646T/AT/CT — P54/74FCT648T/AT/CT OCTAL TRANSCEIVER/REGISTER

## FEATURES

- Function, Pinout and Drive Compatible with the FCT and F Logic
- FCT-C speed at 5.4ns max. (Com'l)  
FCT-A speed at 6.3ns max. (Com'l)
- Reduced  $V_{OH}$  (typically = 3.3V) versions of Equivalent FCT functions
- Edge-rate Control Circuitry for Significantly Improved Noise Characteristics
- ESD protection exceeds 2000V
- Power-off disable feature
- Matched Rise and Fall times
- Fully Compatible with TTL Input and Output Logic Levels
- 64 mA Sink Current (Com'l), 48 mA (Mil)  
15 mA Source Current (Com'l), 12 mA (Mil)
- Independent Register for A and B Buses
- 3-State Output
- Manufactured in 0.7 micron PACE Technology™

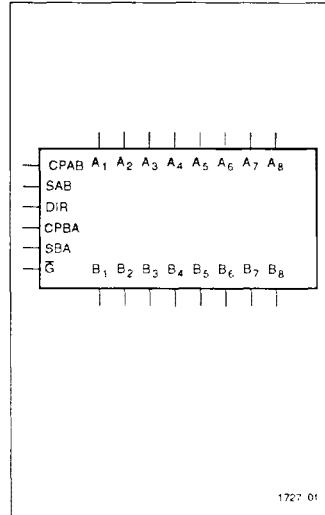
## DESCRIPTION

The 'FCT646T and 'FCT648T consist of a bus transceiver circuit with 3-state, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus will be clocked into the registers as the appropriate clock pin goes to a high logic level. Enable Control G and direction pins are provided to control the transceiver function.

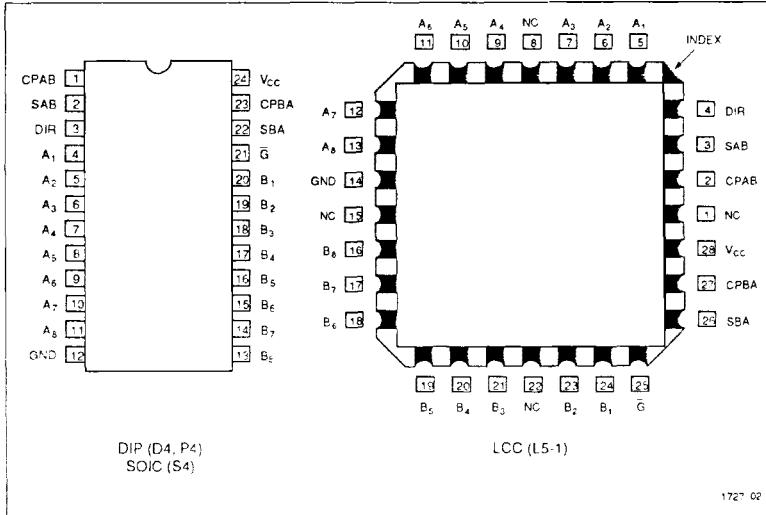
In the transceiver mode, data present at the high impedance port may be stored in either the A or B register, or in both. The select controls can multiplex stored and real-time (transparent mode) data. The direction control determines which bus will receive data when the enable control G is Active LOW. In the isolation mode (enable Control G HIGH), A data may be stored in the B register and/or B data may be stored in the A register.

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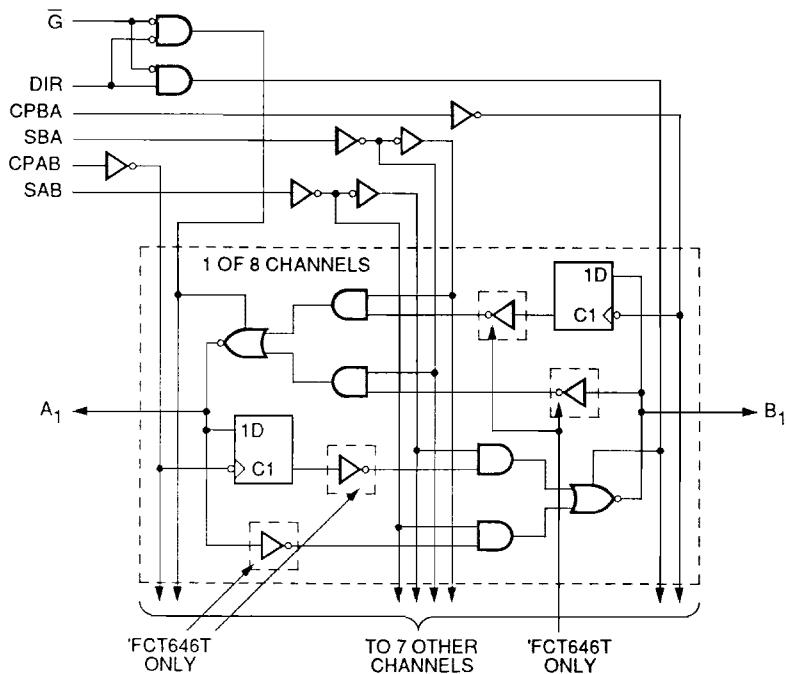
## LOGIC SYMBOL



## PIN CONFIGURATIONS



## FUNCTIONAL BLOCK DIAGRAM

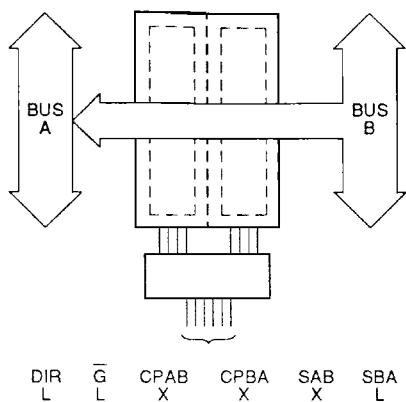


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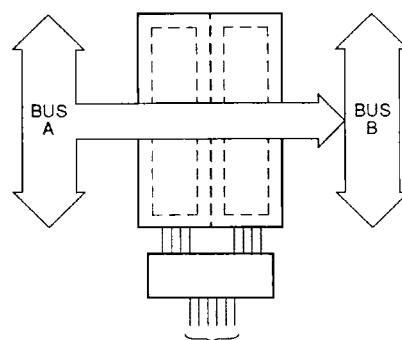
## PIN DESCRIPTION

Pin Names	Description
A <sub>1</sub> - A <sub>8</sub>	Data Register A Inputs Data Register B Outputs
B <sub>1</sub> - B <sub>8</sub>	Data Register B Inputs Data Register A Outputs
CPAB, CPBA	Clock Pulse Inputs
SAB, SBA	Output Data Source Select Inputs
DIR, G	Output Enable Inputs

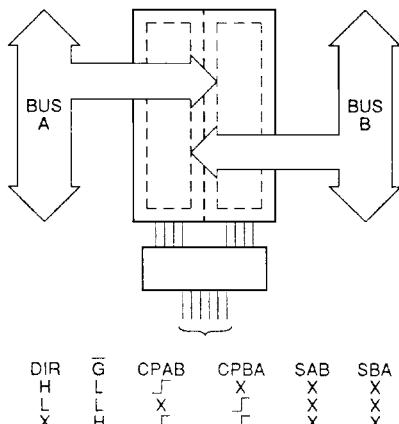
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REAL-TIME TRANSFER  
BUS B TO BUS A

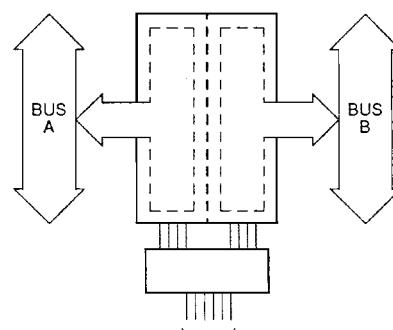
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REAL-TIME TRANSFER  
BUS A TO BUS B

1727 05

STORAGE FROM  
A AND/OR B

1727 06

TRANSFER STORED  
DATA TO A AND/OR B

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## Note:

1. Cannot transfer data to A bus and B bus simultaneously.

## FUNCTION TABLE

Inputs						Data I/O <sup>1</sup>		Operation or Function	
G	DIR	CPAB	CPBA	SAB	SBA	A <sub>1</sub> thru A <sub>8</sub>	B <sub>1</sub> thru B <sub>8</sub>	'FCT646T	'FCT648T
H	X	H or L	H or L	X	X	Input	Input	Isolation Store A and B Data	Isolation Store A and B Data
H	X			X	X				
L	L	X	X	X	L			Real Time B Data to A Bus Stored B Data to A Bus	Real Time B Data to A Bus Stored B Data to A Bus
L	L	X	H or L	X	H	Output	Input		
L	H	X	X	L	X			Real Time A Data to B Bus Stored A Data to B Bus	Real Time A Data to B Bus Stored A Data to B Bus
L	H	H or L	X	H	X	Input	Output		

## Notes:

1. The data output functions may be enabled or disabled by various signals at the G or DIR inputs. Data input functions are always enabled, i.e., data at the bus pins will be stored on every LOW-to-HIGH transition of the clock inputs.
2. H = HIGH, L = LOW, X = Don't Care, T = LOW-to-HIGH Transition.

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**ABSOLUTE MAXIMUM RATINGS<sup>1,2</sup>**

Symbol	Parameter	Value	Unit
$T_{STG}$	Storage Temperature	-65 to +150	°C
$T_A$	Ambient Temperature Under Bias	-65 to +135	°C
$V_{CC}$	$V_{CC}$ Potential to Ground	-0.5 to +7.0	V
$P_T$	Power Dissipation	0.5	W

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**Notes:**

1. Operation beyond the limits set forth in the above table may impair the useful life of the device. Unless otherwise noted, these limits are over the operating free-air temperature range.

Symbol	Parameter	Value	Unit
$I_{OUTPUT}$	Current Applied to Output	120	mA
$V_{IN}$	Input Voltage	-0.5 to +7.0	V
$V_{OUT}$	Voltage Applied to Output	-0.5 to +7.0	V

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2. Unused inputs must always be connected to an appropriate logic voltage level, preferably either  $V_{CC}$  or ground.

**RECOMMENDED OPERATING CONDITIONS**

Free Air Ambient Temperature	Min	Max
Military	-55°C	+125°C
Commercial	0°C	+70°C

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Supply Voltage ( $V_{CC}$ )	Min	Max
Military	+4.5V	+5.5V
Commercial	+4.75V	+5.25V

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**DC ELECTRICAL CHARACTERISTICS** (Over recommended operating conditions)

Symbol	Parameter		Min	Typ <sup>1</sup>	Max	Units	$V_{CC}$	Conditions
$V_{IH}$	Input HIGH Voltage		2.0			V		
$V_{IL}$	Input LOW Voltage				0.8	V		
$V_H$	Hysteresis <sup>3</sup>			0.2		V		All inputs
$V_{IK}$	Input Clamp Diode Voltage			-0.7	-1.2	V	MIN	$I_{IN} = -18\text{mA}$
$V_{OH}$	Output HIGH Voltage	Military Commercial	2.4 2.4	3.3 3.3		V	MIN MIN	$I_{OH} = -12\text{mA}$ $I_{OH} = -15\text{mA}$
$V_{OL}$	Output LOW Voltage	Military Commercial		0.3 0.3	0.55 0.55	V	MIN MIN	$I_{OL} = 48\text{mA}$ $I_{OL} = 64\text{mA}$
$I_I$	Input HIGH Current				20	$\mu\text{A}$	MAX	$V_{IN} = V_{CC}$
$I_{IH}$	Input HIGH Current (Except I/O Pins)				5	$\mu\text{A}$	MAX	$V_{IN} = 2.7\text{V}$
$I_{IL}$	Input LOW Current (Except I/O Pins)				-5	$\mu\text{A}$	MAX	$V_{IN} = 0.5\text{V}$
$I_{IH}$	Input HIGH Current (I/O Pins only)				15	$\mu\text{A}$	MAX	$V_{OUT} = 2.7\text{V}$
$I_{IL}$	Input LOW Current (I/O Pins only)				-15	$\mu\text{A}$	MAX	$V_{OUT} = 0.5\text{V}$
$I_{OS}$	Output Short Circuit Current <sup>2</sup>		-60	-120	-225	mA	MAX	$V_{OUT} = 0.0\text{V}$
$I_{OFF}$	Power-off Disable				100	$\mu\text{A}$	0V	$V_{OUT} = 4.5\text{V}$
$C_{IN}$	Input Capacitance <sup>3</sup>			6	10	pF	MAX	All inputs
$C_{IO}$	I/O Capacitance <sup>3</sup>			8	12	pF	MAX	All outputs
$I_{CC}$	Quiescent Power Supply Current			0.2	1.5	mA	MAX	$V_{IN} \leq 0.2\text{V}$ , $V_{IN} \geq V_{CC} - 0.2\text{V}$

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**Notes:**

1. Typical limits are at  $V_{CC} = 5.0\text{V}$ ,  $T_A = +25^\circ\text{C}$  ambient  
 2. Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high speed test apparatus and/or sample and hold techniques are preferable in order to minimize internal chip heating and more accurately reflect

operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests,  $I_{OS}$  tests should be performed last.

3. This parameter is guaranteed but not tested

**DC CHARACTERISTICS** (Over recommended operating conditions unless otherwise specified.)

Symbol	Parameter	Typ <sup>1</sup>	Max	Units	Conditions
$\Delta I_{CC}$	Quiescent Power Supply Current (TTL inputs)	0.5	2.0	mA	$V_{CC} = \text{MAX}$ , $V_{IN} = 3.4V^2$ , $f_1 = 0$ , Outputs Open
$I_{CCD}$	Dynamic Power Supply Current <sup>3</sup>	0.15	0.25	mA/mHz	$V_{CC} = \text{MAX}$ , One Input Toggling, 50% Duty Cycle, Outputs Open, $\bar{G} = \text{DIR} = \text{GND}$ , or $GAB = \overline{GBA} = \text{GND}$ , $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$
$I_C$	Total Power Supply Current <sup>5</sup>	1.7	4.0	mA	$V_{CC} = \text{MAX}$ , $f_0 = 10\text{MHz}$ , 50% Duty Cycle, Outputs Open, One Bit Toggling at $f_1 = 5\text{MHz}$ , $\bar{G} = \text{DIR} = \text{GND}$ , or $GAB = \overline{GBA} = \text{GND}$ , $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$
		2.2	6.0	mA	$V_{CC} = \text{MAX}$ , $f_0 = 10\text{MHz}$ , 50% Duty Cycle, Outputs Open, One Bit Toggling at $f_1 = 5\text{MHz}$ , $\bar{G} = \text{DIR} = \text{GND}$ , or $GAB = \overline{GBA} = \text{GND}$ , $V_{IN} = 3.4V$ or $V_{IN} = \text{GND}$
		7.0	12.8 <sup>4</sup>	mA	$V_{CC} = \text{MAX}$ , $f_0 = 10\text{MHz}$ , 50% Duty Cycle, Outputs Open, Eight Bits Toggling at $f_1 = 5\text{MHz}$ , $\bar{G} = \text{DIR} = \text{GND}$ , or $GAB = \overline{GBA} = \text{GND}$ , $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$
		9.2	21.8 <sup>4</sup>	mA	$V_{CC} = \text{MAX}$ , $f_0 = 10\text{MHz}$ , 50% Duty Cycle, Outputs Open, Eight Bits Toggling at $f_1 = 5\text{MHz}$ , $\bar{G} = \text{DIR} = \text{GND}$ , or $GAB = \overline{GBA} = \text{GND}$ , $V_{IN} = 3.4V$ or $V_{IN} = \text{GND}$

**Notes:**

1. Typical values are at  $V_{CC} = 5.0V$ , +25°C ambient.
2. Per TTL driven input ( $V_{IN} = 3.4V$ ); all other inputs at  $V_{CC}$  or GND.
3. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
4. Values for these conditions are examples of the  $I_{CC}$  formula. These limits are guaranteed but not tested.
5.  $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$   
 $I_C = I_{CC} + \Delta I_{CC} D_H N_T + I_{CCD} (f_0/2 + f_1 N_1)$   
 $I_{CC}$  = Quiescent Current with CMOS input levels  
 $\Delta I_{CC}$  = Power Supply Current for a TTL High Input ( $V_{IN} = 3.4V$ )

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 $D_H$  = Duty Cycle for TTL Inputs High $N_T$  = Number of TTL Inputs at  $D_H$  $I_{CCD}$  = Dynamic Current Caused by an Input Transition Pair (LHL or LHL) $f_0$  = Clock Frequency for Register Devices (Zero for Non-Register Devices) $f_1$  = Input Frequency $N_1$  = Number of Inputs at  $f_1$ 

All currents are in millamps and all frequencies are in megahertz.

## AC CHARACTERISTICS

Symbol	Parameter	'FCT646T/648T				'FCT646AT/648AT				'FCT646CT/648CT				Units	Fig. No.		
		MIL		COM'L		MIL		COM'L		MIL		COM'L					
		Min. <sup>1</sup>	Max.														
$t_{PLH}$ $t_{PHL}$	Propagation Delay Bus to Bus	2.0	11.0	2.0	9.0	2.0	7.7	2.0	6.3	1.5	6.0	1.5	5.4	ns	1, 3		
$t_{PZH}$ $t_{PZL}$	Output Enable Time Enable to Bus and DIR to A or B	2.0	15.0	2.0	14.0	2.0	10.5	2.0	9.8	1.5	8.9	1.5	7.8	ns	1, 7, 8		
$t_{PHZ}$ $t_{PLZ}$	Output Disable Time G to Bus and DIR to Bus	2.0	11.0	2.0	9.0	2.0	7.7	2.0	6.3	1.5	7.7	1.5	6.3	ns	1, 7, 8		
$t_{PLH}$ $t_{PHL}$	Propagation Delay Clock to Bus	2.0	10.0	2.0	9.0	2.0	7.0	2.0	6.3	1.5	6.3	1.5	5.7	ns	1, 5		
$t_{PLH}$ $t_{PHL}$	Propagation Delay SBA or SAB to A or B	2.0	12.0	2.0	11.0	2.0	8.4	2.0	7.7	1.5	7.0	1.5	6.2	ns	1, 5		

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## Note:

1. AC Characteristics guaranteed with  $C_L = 50\text{pF}$  as shown in Figure 1.

## AC OPERATING REQUIREMENTS

Symbol	Parameter	'FCT646T/648T				'FCT646AT/648AT				'FCT646CT/648CT				Units	Fig. No.		
		MIL		COM'L		MIL		COM'L		MIL		COM'L					
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.				
$t_s(H)$ $t_s(L)$	Setup Time HIGH or LOW Bus to Clock	4.5	—	4.0	—	2.0	—	2.0	—	2.0	—	2.0	—	ns	4		
$t_h(H)$ $t_h(L)$	Hold Time HIGH or LOW Bus to Clock	2.0	—	2.0	—	1.5	—	1.5	—	1.5	—	1.5	—	ns	4		
$t_w(H)$ $t_w(L)$	Pulse Width, HIGH or LOW	6.0	—	6.0	—	5.0	—	5.0	—	5.0	—	5.0	—	ns	5		

## Note:

1. Minimum limits are guaranteed but not tested on Propagation Delays

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## ORDERING INFORMATION

PxxFCT	xxxx	x	x
Temp. Class	Device type	Package	Processing

					Blank	Commercial
					M	Military Temperature
					B	MIL-STD-883, Class B
					P	Plastic DIP
					D	CERDIP
					SO	Small Outline IC
					L	Leadless Chip Carrier
					646T	Non-inverting Octal Transceiver/Register
					646AT	Fast Non-inverting Octal Transceiver/Register
					646CT	Ultra Fast Non-inverting Octal Transceiver/Register
					648T	Inverting Octal Transceiver/Register
					648AT	Fast Inverting Octal Transceiver/Register
					648CT	Ultra Fast Inverting Octal Transceiver/Register
					74	Commercial
					54	Military

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